

**PART INFORMATION**

Mfg Item Number	MCIMX6Y0CVM05AB
Mfg Item Name	MAP289 14*14*1.4P.8T1.32

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-01-06
Response Document ID	00M8A1.1
Contact Name	Freescale Semiconductor Inc
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**DECLARATION**

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

**MANUFACTURING**

Mfg Item Number	MCIMX6Y0CVM05AB
Mfg Item Name	MAP289 14*14*1.4P.8T1.32
Version	ALL
Weight	0.451400
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0017						g				
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0001275	g	75000	7.5	282	0.0282
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00034	g	200000	20	753	0.0753
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0001275	g	75000	7.5	282	0.0282
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00034	g	200000	20	753	0.0753
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.000765	g	450000	45	1694	0.1694
Solder Balls - Lead Free	0.0744						g				
Solder Balls - Lead Free		Metals	Aluminum, metal	7429-90-5		0.00000074	g	10	0.001	1	0.0001
Solder Balls - Lead Free		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.0000372	g	500	0.05	82	0.0082
Solder Balls - Lead Free		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.0000232	g	300	0.03	49	0.0049
Solder Balls - Lead Free		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.0000232	g	300	0.03	49	0.0049
Solder Balls - Lead Free		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.00000149	g	20	0.002	3	0.0003
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.000372	g	5000	0.5	824	0.0824
Solder Balls - Lead Free		Metals	Iron, metal	7439-89-6		0.00001488	g	200	0.02	32	0.0032
Solder Balls - Lead Free		Lead/Lead Compounds	Lead	7439-92-1		0.0000372	g	500	0.05	82	0.0082
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.000744	g	10000	1	1648	0.1648
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.07314711	g	983160	98.316	162044	16.2044
Solder Balls - Lead Free		Metals	Zinc, metal	7440-66-6		0.00000074	g	10	0.001	1	0.0001
Bonding Wire, PdCu	0.0014						g				
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.00137339	g	980994	98.0994	3042	0.3042
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000014	g	1000	0.1	3	0.0003
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.00002521	g	18006	1.8006	55	0.0055
Die Encapsulant, Halogen-free	0.2269						g				
Die Encapsulant, Halogen-free		Metals	Aluminum, metal	7429-90-5		0.0056725	g	25000	2.5	12566	1.2566
Die Encapsulant, Halogen-free		Metals	Magnesium, metal	7439-96-4		0.002269	g	10000	1	5026	0.5026
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.002269	g	10000	1	5026	0.5026
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.0260935	g	115000	11.5	57805	5.7805
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.002269	g	10000	1	5026	0.5026
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.18152	g	800000	80	402147	40.2147
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other acrylic/epoxy resin mixture	-		0.0011345	g	5000	0.5	2513	0.2513
Die Encapsulant, Halogen-free		Glass	Silica, amorphous synthetic	112926-00-8		0.0056725	g	25000	2.5	12566	1.2566
Organic Substrate, Halogen-free	0.1393						g				
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (2574)	68891-46-3		0.001393	g	10000	1	3085	0.3085
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.01393	g	100000	10	30859	3.0859
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		0.0210343	g	151000	15.1	46597	4.6597
Organic Substrate, Halogen-free		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.03517325	g	252500	25.25	77920	7.792
Organic Substrate, Halogen-free		Metals	Gold, metal	7440-57-5		0.0016716	g	12000	1.2	3703	0.3703
Organic Substrate, Halogen-free		Nickel (external applications only)	Nickel	7440-02-0		0.008358	g	60000	6	18515	1.8515
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.0072436	g	52000	5.2	16046	1.6046
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.03432	g	240000	24	74062	7.4062
Organic Substrate, Halogen-free		Glass	Silica amorphous	61790-53-2		0.01706425	g	122500	12.25	37802	3.7802
Silicon Semiconductor Die	0.0077						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000154	g	20000	2	341	0.0341
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.007546	g	980000	98	16716	1.6716

## LINKS

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MCIMX6Y0CVM05AB\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MCIMX6Y0CVM05AB_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MCIMX6Y0CVM05AB\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MCIMX6Y0CVM05AB_IPC1752A.xml)